

semiconductor packaging news

search

We search for industry news so you don't need to.

2023 Media Guide

semiconductor packaging news

We search for industry news, so you don't need to.

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Inside TSMC's New Plant in Phoenix

As the world grapples with an ongoing chip shortage, a quiet giant among chipmakers has committed to investing \$100 billion over three years to ramp up production. Taiwan Semiconductor Manufacturing Company may not be a household name, but with a market value of over \$550 billion, it's one of the world's 10 most valuable companies. Now, it's leveraging its considerable resources to bring ...

CNBC



Improve 3DIC Implementation & Signoff

Find out how the industry's first high-capacity platform enables 3D design planning, implementation, and system analysis into a single, unified cockpit.



Cadence Design Systems, Inc.

BGA Component Reball Video

Video demonstrates touch-less BGA component solder ball removal. This precision process is highly reliable when preparing BGA components prior to reballing.



Circuit Technology Center

Persisting chip shortage

South Korea's automotive and electronics industries are bearing the brunt of the persisting global semiconductor shortage. More worrisome is that the chip crunch shows ...

The Korea Times

Innovations in Wire Bond Inspection

New 3D inspection system is specifically designed to meet the challenges of wire bonding. Among its features are substantially improved sensors, a high image ...

Technical Paper

Intel CEO wants to compete against Apple

Intel CEO Pat Gelsinger hasn't given up on the idea of the Mac once again using Intel chips, but he acknowledges it will probably be years before he gets that chance. ...

AOL

Technical Papers

- How to Wire Pull?
- Monolithic Magnetic Sensors Manufactured by Selective Laser Annealing
- Maximizing Protection of Flip Chip Interconnects
- Automated Control of Chiplet Placement
- XRF for Thin Films & Solders in the Semiconductor Industry
- Balancing Throughput and Process Control for RF Power Amplifier Assemblies
- Hermetic Package Lowest Fine Leak Rates

5 Billion ~ the Proven SiP Materials

With our products in more than 5 billion SiP packages, Indium Corporation's portfolio of proven materials meets current and evolving challenges encountered in SiP applications.



Indium Corporation

Superior Wafer Imaging, Faster Throughput

Sonic AutoWafer™ provides leading image quality, resolution, accuracy, data analysis and throughput for subsurface inspection. See the difference.



Sonic, Inc.

Electronic System Design Industry Logs Double-Digit Q2 2021 Year-Over-Year Revenue Growth, ESD Alliance Reports

Electronic System Design (ESD) industry revenue increased 14.6% year-over-year from \$2,783.9 million to \$3,191.4 million in Q2 2021, the ESD Alliance announced in the ...

3DInCites

Taiwan's IC strength could spur Chinese takeover: IC Insights

Taiwan has more semiconductor capacity than any other economy in the world, and that strength could prompt China to take it over amid growing tensions between ...

Focus Taiwan

TSMC to Build Chip Fab in Japan

After a week of media rumor, leaks and speculation, Taiwan Semiconductor Manufacturing Co. (TSMC), the world's largest contract chip manufacturer, announced in an ...

IEEE Spectrum

New insights with integrated metrology

SUSS MicroTec's new TM200/300 metrology modules reveal a clear picture of the coating process, automate tool qualification in HVM fabs and ensure precise process performance. Read more.

SUSS MicroTec SE

Today's Sponsor



Test Your Knowledge

Which of these famous science fiction writers played a part in the development of radar? H. G. Wells, Isaac Asimov, or Arthur C. Clark. See answer below.

Shortage defense grade FPGA could result in warfighters not flying

Govt documents indicate FPGA devices rely on a single source subcontractor to provide column attachment services. Sustainability in question.

TopLine

Press Releases

Non-Cytotoxic Epoxy Resists Sterilization by Autoclaving, Radiation and Chemicals

Master Bond EP62-IHTMed is a two part epoxy that meets the requirements of ISO 10993-5 for non-cytotoxicity and therefore can be utilized in many medical device applications. ...

Master Bond

FHP Reps to Represent YXLON International X-ray Portfolio

YXLON International is pleased to announce the appointment of FHP Reps as its representative throughout Texas, Oklahoma, Arkansas, Louisiana, Missouri, Nebraska and Kansas. ...

YXLON International

Xperi Licenses Hybrid Bonding Technology to Yangtze Memory Technologies Co., Ltd.

Xperi Holding Corporation™ announced that the company entered into a license agreement with Yangtze Memory Technologies Co., Ltd. (YMT), a world-class memory solutions ...

Xperi Holding Corporation™

Broad Market Applications

QP Technologies develops packaging and assembly solutions for a wide range of end markets, including commercial, industrial, automotive, med/bio/tech and mil-aero.



QP Technologies

Quote of the Day

"Whenever you find yourself on the side of the majority, it's time to pause and reflect."

Mark Twain

Broad Market Applications

QP Technologies develops packaging and assembly solutions for a wide range of end markets, including commercial, industrial, automotive, med/bio/tech and mil-aero.



- 30,000+ daily e-mail subscribers
- 125,000 unique visitors past 12 months
- Readership from 140 countries
- #1 newsletter and website for industry professionals



Why Advertise With Semiconductor Packaging News?

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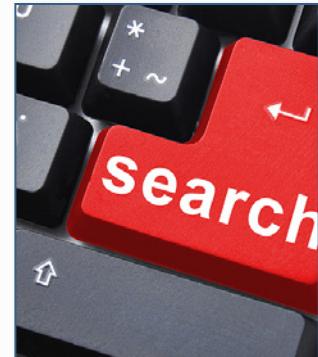
Electronic-media continues to expand as industry professionals seek daily updates on news and events shaping the semiconductor packaging and micro-electronics market. An advertising campaign in Semiconductor Packaging News provides excellent visibility with high-frequency advertising designed to meet every budget. We reach 125,000 industry professionals who are eager to learn more about your products and services.

A digital advertising campaign features:

- Lead generation and advertising in the daily newsletter & website
- Banner ads for branding (160 x 300 pixels vertical)
- Text ads intrigue readers to click to your web pages to learn more
- Technical papers provide lead generation for your sales channel
- Corporate news releases published daily at no cost
- Calendar to post your shows, webcasts and important events
- Custom e-mail broadcast to our subscribers dedicated to your company

Analytical Data

Recent analytical data collected from an independent company confirms our readership continues to expand. Semiconductor Packaging News e-mail newsletter is broadcast to over 30,000 subscribers every business day.



During the past 12-months Semiconductor Packaging News has reached over 125,000 unique visitors from 140 countries. The e-mail newsletter subscriber base is always up-to-date and is managed by an independent e-mail company.

Top 10 markets by geographic readership:

- | | |
|-----------------|------------------|
| ▪ North America | ▪ China |
| ▪ Japan | ▪ Germany |
| ▪ South Korea | ▪ Netherlands |
| ▪ Taiwan | ▪ France |
| ▪ Singapore | ▪ United Kingdom |

Demographics by region of the world:
50% Americas, 30% Asia Pacific, and 20% Europe

Industry organizations such as SEMI, IMAPS, MEPTEC, IEEE partner with Semiconductor Packaging News to reach their members and drive visitors to their events and trade shows.

Comments from several Semiconductor Packaging News advertisers:

"SPN provides a great opportunity to reach a range of prospects on a daily basis for a very competitive price. We can advertise for an entire year for the cost of a small booth at a local show".

J.B.

"The White Paper program in SPN has delivered hundreds of prospects from around the world. This is a great way to reach new customers".

R.H.

"We are very pleased with the exposure and support from our ad campaign in SPN"

D.P.

"Semiconductor Packaging allows us to reach our markets around the globe. We book new orders from readers of SPN".

J.F.

"In this period of decline in print publications, our users are turning to the web as the source of information. We have benefited from our aggressive use of SPN as an advertising vehicle".

R.B.

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Semiconductor Packaging News Readers

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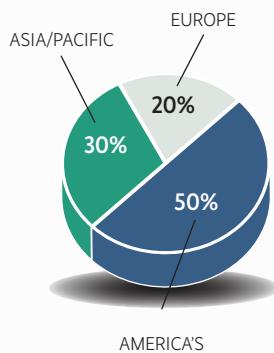
Over 30,000 daily subscribers find Semiconductor Packaging News to be their go-to source for news and information in the semiconductor and micro-electronics assembly market. Semiconductor Packaging News subscribers and website visitors are the industry professionals you want to reach; they are your prospects and your customers.

Rather than waiting for an issue of a trade publication every month or two, our daily e-mail broadcast reaches professionals that have a need to know – and who bear the responsibility for looking ahead to keep their companies on top! They keep themselves up to speed by reading Semiconductor Packaging News daily. Over 500,000 articles have been clicked and read by Semiconductor Packaging News readers.

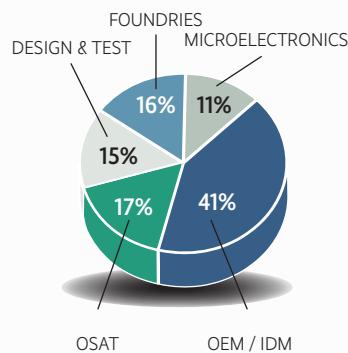


Based on a readership survey we are proud to share data and commentary from industry professionals who took part in our survey.

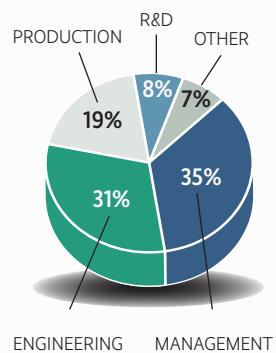
Readership
Breakdown



Company Type



Job Description



Comments from several Semiconductor Packaging News subscribers:

"Semiconductor Packaging News is the only daily newsletter focused on the packaging side of the industry".

"SPN is the best daily newsletter, I look forward to reading each day".

"This is the best daily newsletter for insight on the micro-electronics and semiconductor industries."

"I read SPN regularly and find the mix of information to be quite interesting".

"As an Asia Pacific reader, I find your newsletter useful to gain the global perspective on the growing 3D packaging".

"All the important news in one place, great way to start my morning".

Nice Job. Really stands out. Very newsy with lots of good stuff.

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Advertising Opportunities

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Semiconductor Packaging News advertising delivers results. We deliver your message to a targeted readership with the highest frequency. Advertising campaigns in Semiconductor Packaging News provide more visibility compared to other weekly newsletters and print media. The more often your ads run, the more response you will receive.

Banner Ads

Banner Ads are ideal for branding with corporate colors and a company logo. Large banner ads (160 x 300 pixels) provide significant space to deliver your messages for maximum exposure.

Text Ads

A well written text ad will intrigue the reader to click the ad to learn more about your product or service. The goal of a text ad is to deliver readers directly to your website. We encourage advertisers to run multiple text ads in their ad campaign at no extra cost.

Top Sponsor Position

Gold and silver-plus sponsors will have “text ad” at the top of the newsletter and website once each month. Company logo also appears in the top right column “Today’s Sponsor” on the same day. Gold and silver-plus advertisers also receive premium positions each month.

Technical Papers generate leads each month

Semiconductor Packaging publishes relevant technical papers at no cost allowing readers to download them with a simple registration. We gather the name, company and e-mail addresses and provide to our advertisers at no additional cost.

Geo-Targeting

The geo-targeting feature allows your banner ads and text ads to be delivered to readers in a specific continent or country. A great method to reach a select group of readers to introduce a new product to a specific market, publicize a webinar or promote an award, ask for more details.

Custom E-mail Broadcast

A custom e-mail broadcast to our subscribers can showcase new products, promote a webinar, conference or award. The custom e-mail broadcast will be focused exclusively on your company, ask us for more details.



Monthly Media Reports

Semiconductor Packaging News provides a monthly media report capturing data from your campaign including banner ad and text ad impressions and clicks. We also gather the names of readers who download the published technical papers to share with your sales channel.

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Amkor Technology

To view monthly reports for advertisements in the Semiconductor Packaging News email newsletter.

Monthly Reports

[Sep 2021](#), [Aug 2021](#), [Jul 2021](#), [Jun 2021](#), [May 2021](#), [Apr 2021](#), [Mar 2021](#),
[Mar 2021](#), [Feb 2021](#), [Jan 2021](#), [Dec 2020](#), [Nov 2020](#), [Oct 2020](#), [Oct 2020](#),
[Sep 2020](#), [Sep 2020](#), [Aug 2020](#), [Aug 2020](#), [Jul 2020](#), [Jun 2020](#), [May 2020](#),
[Apr 2020](#), [Mar 2020](#), [Mar 2020](#), [Feb 2020](#), [Feb 2020](#), [Jan 2020](#), [Jan 2020](#),
[Dec 2019](#), [Nov 2019](#), [Nov 2019](#), [Oct 2019](#), [Oct 2019](#), [Sep 2019](#), [Sep 2019](#),
[Aug 2019](#), [Jul 2019](#), [Jun 2019](#), [May 2019](#), [Apr 2019](#), [Mar 2019](#), [Feb 2019](#),
[Jan 2019](#), [Dec 2018](#), [Nov 2018](#), [Oct 2018](#), [Sep 2018](#), [Aug 2018](#), [Jul 2018](#),
[Jun 2018](#), [May 2018](#), [Apr 2018](#), [Mar 2018](#), [Mar 2018](#), [Feb 2018](#), [Feb 2018](#),
[Jan 2018](#), [Jan 2018](#), [Dec 2017](#), [Dec 2017](#), [Nov 2017](#), [Nov 2017](#), [Oct 2017](#),
[Sep 2017](#), [Sep 2017](#), [Aug 2017](#), [Aug 2017](#), [Jul 2017](#), [Jun 2017](#), [May 2017](#),
[Apr 2017](#), [Mar 2017](#), [Feb 2017](#), [Jan 2017](#)

Recent Press Releases

Submit

Date	Title	Submit
Aug 23, 2021	Amkor's DSMBGA Advanced SiP Platform is the Preferred Packaging for 5G RF	
Aug 17, 2021	Amkor Empowers RF Front-End Cellular Innovations with Advanced SiP	
Jul 28, 2021	Amkor Technology Reports Financial Results for the Second Quarter 2021	
Feb 24, 2021	Amkor Factory Intelligence Enables Industry 4.0	
Feb 9, 2021	Amkor Technology Reports Financial Results for the Fourth Quarter and Full Year 2020	

Recent Technical/White Papers

Submit

Click "List" to see who downloaded your White Paper.

Date	Title	List
Oct 19, 2021	Qualifying the ExposedPad TQFP for AEC-Q006 Grade 0	List
Jun 18, 2021	Will an Adhesion Promoter Prevent Delamination in Power Semiconductor Packages?	List
Apr 13, 2021	Advantages of Outsourced Test Services	List
Jan 26, 2021	Adding Value with Unit Level Traceability (ULT) in Automotive Packaging	List
Dec 14, 2020	Side Wettable Flanks for Leadless Automotive Packaging	List

Did You Know: Text ads will typically deliver 2-3 times as many clicks as a banner ad. Advertisers use banner ads to build the company brand and text ads to drive readers to pages on their website.

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Rate Card

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Premium Positions

Sponsor Text Ad

Sponsor Logo

Premium Position

Text Ad

Text Ad

Vertical Banner Ads

Text Ad

Silver Campaign

The Silver Campaign includes 8 days per month in the e-mail newsletter. Ads will usually run twice per week in this campaign. This campaign does not include visibility in the website.

6-month campaign \$1,050/month
12-month campaign \$950/month
(Credit card pricing)

Silver-Plus Campaign

The Silver-Plus Campaign includes 9 day per month in the e-mail newsletter including a premium ad position each month plus your campaign runs on the website 24/7.

6-month campaign \$1,450/month
12-month campaign \$1,350/month
(Credit card pricing)

Gold Campaign

The Gold Campaign includes 15 days per month in the e-mail newsletter including a top sponsor position with company logo each month plus your campaign runs on the website 24/7.

6-month campaign \$1900/month
12-month campaign \$1800/month
(Credit card pricing)

The screenshot shows the homepage of Semiconductor Packaging News. At the top, there's a banner with three smiling people. Below it, the main navigation menu includes 'HOME', 'PAPERS', 'SUBSCRIBE', and 'TRANSLATE'. The main content area features several news stories:

- Inside TSMC's New Plant in Phoenix**: A story about Taiwan Semiconductor Manufacturing Company's new plant in Phoenix, mentioning a chip shortage and its investment of over \$100 billion.
- Improve 3DIC Implementation & Signoff**: An article from Cadence Design Systems, Inc., discussing the first high-capacity platform for 3D design planning, implementation, and system analysis.
- Persisting chip shortage**: A story from The Korea Times about the global semiconductor shortage.
- Innovations in Wire Bond Inspection**: A story from Technical Paper about a new 3D inspection system for wire bonding.
- Intel CEO wants to compete against Apple**: A story from AXIOS about Intel's CEO Pat Gelsinger's interest in competing with Apple.
- Technical Papers**: A section listing various technical papers such as 'How to Write Pulls', 'Microfluidic Housing Sensors Manufactured by Selective Laser Annealing', etc.
- 5 Billion – the Proven SIP Materials**: An article from Indium Corporation about their proven materials for SIP applications.
- Electronic System Design Industry Logs Double-Digit Q2 2021 Year-Over-Year Revenue Growth, ESD Alliance Reports**: A story from 3DInCites about the ESD Alliance reporting double-digit revenue growth.
- Taiwan's IC strength could spur Chinese takeover: IC Insights**: A story from IEEE Spectrum about Taiwan's semiconductor capacity and its potential impact on China.
- TSMC to Build Chip Fab in Japan**: A story from IEEE Spectrum about Taiwan Semiconductor Manufacturing Co. (TSMC) planning to build a new chip fab in Japan.
- Supporting Long Lifecycle Automotive Applications**: An advertisement for Rochester Electronics featuring Mitsubishi ZEROSHIFT™ Thermistor.
- Mitsubishi ZEROSHIFT™ Thermistor**: A detailed technical article about the thermistor's performance and applications.
- Ankor's Wafer Level Packaging Solutions**: An advertisement for Ankor Technology, Inc., highlighting their broad array of Wafer Level Packaging capabilities.
- What Year Was It?**: A section titled 'Quote of the Day' with a quote from Mark Twain.
- Broad Market Applications**: An advertisement for QP Technologies showing their market coverage across various industries.
- Quote of the Day**: Another quote from Mark Twain.
- U.S. Takes Possession of Alaska**: A brief news item about the U.S. formally taking possession of Alaska.

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About Us

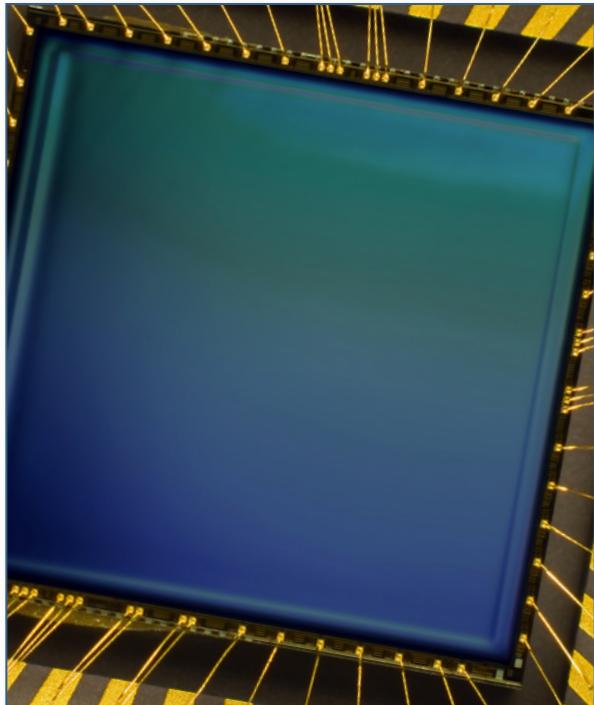
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We believe it's our job to dig through the unending stream of news, articles, features, and discussions to deliver information, covering the world of semiconductor packaging and micro-electronics, to our readers. Every night we scour the news from 150 sources to find the best industry news articles. We package this information into a convenient newsletter that is delivered to our subscribers e-mail every business day.

The Semiconductor Packaging Newsletter and website features links to industry and technology news stories and feature articles about the semiconductor packaging market. We publish the latest corporate and product news announcements industry companies submit to us.

Thousands of technical papers are downloaded every month and we'll publish your technical paper at no cost. You'll also find commentaries, cartoons, an industry event calendar and much more.

We look forward to working with you on your digital sponsorship campaign.



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